## 2SC5939

**Transistors** 

### Silicon NPN epitaxial planar type

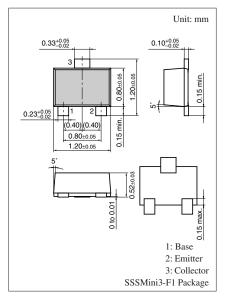
For high-frequency amplification/oscillation/mixing

#### ■ Features

- High transition frequency f<sub>T</sub>
- ullet Small collector output capacitance (Common base, input open circuited)  $C_{ob}$  and reverse transfer capacitance (Common base)  $C_{rb}$
- SSS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                             | Symbol           | Rating      | Unit |  |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V <sub>CBO</sub> | 15          | V    |  |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | 10          | V    |  |
| Emitter-base voltage (Collector open) | $V_{EBO}$        | 3           | V    |  |
| Collector current                     | $I_C$            | 50          | mA   |  |
| Collector power dissipation           | P <sub>C</sub>   | 100         | mW   |  |
| Junction temperature                  | $T_j$            | 125         | °C   |  |
| Storage temperature                   | $T_{stg}$        | -55 to +125 | °C   |  |

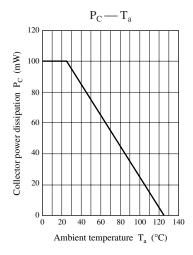


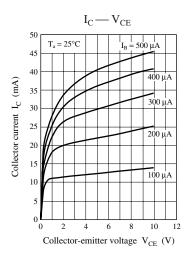
Marking Symbol: 1S

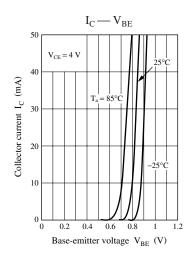
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

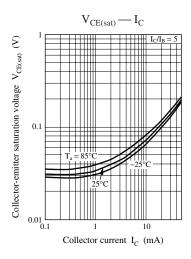
| Parameter                                    | Symbol                             | Conditions   | Min  | Тур  | Max | Unit |
|--|------------------------------------|--|------|------|-----|------|
| Collector-emitter voltage (Base open)        | V <sub>CEO</sub>                   | $I_C = 2 \text{ mA}, I_B = 0$                                      | 10   |      |     | V    |
| Emitter-base voltage (Collector open)        | $V_{EBO}$                          | $I_E = 10 \ \mu A, I_C = 0$  | 3    |      |     | V    |
| Collector-base cutoff current (Emitter open) | $I_{CBO}$                          | $V_{CB} = 10 \text{ V}, I_{E} = 0$                                 |      |      | 1   | μΑ   |
| Forward current transfer ratio               | h <sub>FE</sub>                    | $V_{CE} = 4 \text{ V}, I_C = 5 \text{ mA}$                         | 75   |      | 400 | _    |
| h <sub>FE</sub> ratio                        | $\Delta h_{FE}$                    | $V_{CE} = 4 \text{ V}, I_{C} = 100  \mu\text{A}$                   | 0.75 |      | 1.6 | _    |
|  |                                    | $V_{CE} = 4 \text{ V}, I_C = 5 \text{ mA}$                         |      |      |     |      |
| Collector-emitter saturation voltage         | V <sub>CE(sat)</sub>               | $I_C = 20 \text{ mA}, I_B = 4 \text{ mA}$                          |      |      | 0.5 | V    |
| Transition frequency                         | $f_T$                              | $V_{CE} = 4 \text{ V}, I_{E} = -5 \text{ mA}, f = 200 \text{ MHz}$ | 1.4  | 1.9  | 2.7 | GHz  |
| Collector output capacitance                 | C <sub>ob</sub>                    | $V_{CB} = 4 \text{ V}, I_E = 0, f = 1 \text{ MHz}$                 |      | 1.4  |     | pF   |
| (Common base, input open circuited)          |                                    |  |      |      |     |      |
| Reverse transfer capacitance                 | $C_{rb}$                           | $V_{CB} = 4 \text{ V}, I_E = 0, f = 1 \text{ MHz}$                 |      | 0.45 |     | pF   |
| (Common base)                                |                                    |  |      |      |     |      |
| Collector-base parameter                     | r <sub>bb</sub> ' • C <sub>C</sub> | $V_{CB} = 4 \text{ V}, I_E = -5 \text{ mA}, f = 31.9 \text{ MHz}$  |      | 11   |     | ps   |

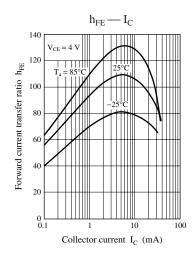
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

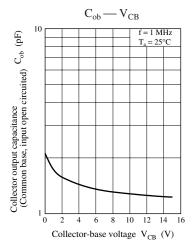












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